CLIPPEDIMAGE= JP360218751A
PAT-NO: JP360218751A
DOCUMENT-IDENTIFIER: JP 60218751 A
TITLE: FLUORESCENT CHARACTER DISPLAY TUBE

PUBN-DATE: November 1, 1985

INVENTOR-INFORMATION:
NAME
YAMAMOTO, JIRO

ASSIGNEE-INFORMATION:
NAME COUNTRY
NEC CORP N/A

APPL-NO: JP59073440
APPL-DATE: April 12, 1984

INT-CL_(IPC): H01J031/15
US-CL-CURRENT: 313/485

ABSTRACT:
PURPOSE: To obtain wire bonding with high reliability without increasing the area necessary for arranging bonding pads by positioning each pair of adjacent bonding pads in counter directions.

CONSTITUTION: Although a conventional bonding pad 2 has a shorter side length of (a) and a longer side length of (b), in this invention, an isosceles(equilateral)- triangle bonding pad 21 having a base length of (2a) and a height of (b) is used. And, each pair of adjacent pads are positioned in counter directions. Therefore, it is possible to form a bonding pad group without changing the distance between the semiconductor element and the bonding pad as well as the distance between the bonding pads almost entirely. In addition, since the base length of the bonding pad 21 is twice that of the conventional bonding pad 2, the sectional shape of the **bonding pad 21 is a trapezoid** and an area effective for wire bonding becomes larger than that for the rectangular bonding pad. Therefore, homogeneous pressure is

applied during
wire bonding.

CLIPPEDIMAGE= JP403133148A
PAT-NO: JP403133148A
DOCUMENT-IDENTIFIER: JP 03133148 A
TITLE: SEMICONDUCTOR DEVICE

PUBN-DATE: June 6, 1991

INVENTOR-INFORMATION:
NAME
YAMADA, MASAHIRO

ASSIGNEE-INFORMATION:
NAME COUNTRY
SEIKO EPSON CORP N/A

APPL-NO: JP01271965
APPL-DATE: October 19, 1989

INT-CL_(IPC): H01L021/60; H01L021/321
US-CL-CURRENT: 29/827

ABSTRACT:
PURPOSE: To enable formation of a pad which minimizes a distance between
adjacent pads by using a **trapezoid pad in an arrangement of a bonding pad** and
by arranging it to make a long side and a short side of the trapezoid opposite
each other alternately.

CONSTITUTION: A trapezoid pad is used and arranged to make a long side (a) and
a short side (b) opposite each other alternately. Accordingly, a pad of a
larger shape than a rectangular one can be arranged deviating bonding centers
of adjacent pads. That is, wire bonding is shaped to acquire higher freedom.
Thereby, it is possible to reduce a pad pitch and to enable easy wire bonding
in comparison with a conventional rectangular pad.

DERWENT-ACC-NO: 1991-211340
DERWENT-WEEK: 199129

TITLE: Bonding pads of semiconductor device - arranges **trapezoidal shape bonding pads** in normal and inversed positions alternately and increases areas of bonding pads NoAbstract Dwg 1/2

PATENT-ASSIGNEE: SEIKO EPSON CORP[SHIH]

PRIORITY-DATA: 1989JP-0271965 (October 19, 1989)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 03133148 A	June 6, 1991	N/A	000	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP03133148A	N/A	1989JP-0271965	October 19, 1989

INT-CL (IPC): H01L021/60
ABSTRACTED-PUB-NO:
EQUIVALENT-ABSTRACTS:

TITLE-TERMS:
BOND PAD SEMICONDUCTOR DEVICE ARRANGE **TRAPEZOID SHAPE BOND PAD** NORMAL INVERSE POSITION ALTERNATE INCREASE AREA BOND PAD NOABSTRACT

DERWENT-CLASS: U11

EPI-CODES: U11-D03B1; U11-D03C1;

SECONDARY-ACC-NO:
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